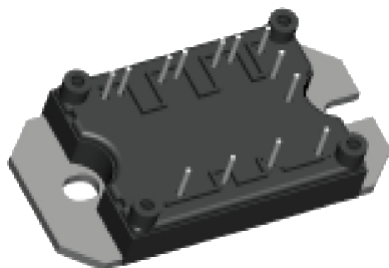


Three Phase Inverter Module in MTP Package 1200 V NPT IGBT and HEXFRED® Diodes, 5 A



MTP

PRODUCT SUMMARY

V_{CES}	1200 V
$V_{CE(on)}$ typical at $V_{GE} = 15$ V	2.90 V
I_C at $T_C = 100$ °C	5 A
t_{sc} at $T_J = 150$ °C	> 10 μ s
Package	MTP
Circuit	Three phase inverter

FEATURES

- Generation 5 NPT 1200 V IGBT technology
- HEXFRED® diode with ultrasoft reverse recovery
- Very low conduction and switching losses
- Optional SMT thermistor (NTC)
- Aluminum oxide DBC
- Very low stray inductance design for high speed operation
- Short circuit 10 μ s
- Square RBSOA
- Operating frequencies 8 kHz to 60 kHz
- UL approved file E78996 
- Designed and qualified for industrial level
- Material categorization: For definitions of compliance please see www.vishay.com/doc?99912


RoHS
COMPLIANT

BENEFITS

- Optimized for inverter motor drive applications
- Low EMI, requires less snubbing
- Direct mounting to heatsink
- PCB solderable terminals
- Very low junction to case thermal resistance

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS
Collector to emitter voltage	V_{CES}		1200	V
Continuous collector current	I_C	$T_C = 25$ °C	12	A
		$T_C = 100$ °C	5	
Pulsed collector current	I_{CM}		24	
Peak switching current	I_{LM}		24	
Diode continuous forward current	I_F	$T_C = 100$ °C	5	
Peak diode forward current	I_{FM}		12	V
Gate to emitter voltage	V_{GE}		± 20	
RMS isolation voltage	V_{ISOL}	Any terminal to case, $t = 1$ min	2500	W
Maximum power dissipation (including diode and IGBT)	P_D	$T_C = 25$ °C	76	
		$T_C = 100$ °C	31	



ELECTRICAL SPECIFICATIONS ($T_J = 25\text{ }^{\circ}\text{C}$ unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Collector to emitter breakdown voltage	$V_{(BR)CES}$	$V_{GE} = 0\text{ V}$, $I_C = 250\text{ }\mu\text{A}$	1200	-	-	V
Temperature coefficient of $V_{(BR)CES}$	$\Delta V_{(BR)CES}/\Delta T_J$	$V_{GE} = 0\text{ V}$, $I_C = 1\text{ mA}$ ($25\text{ }^{\circ}\text{C}$ to $125\text{ }^{\circ}\text{C}$)	-	1.14	-	V/ $^{\circ}\text{C}$
Collector to emitter voltage	$V_{CE(on)}$	$V_{GE} = 15\text{ V}$, $I_C = 6\text{ A}$	-	2.90	3.17	V
		$V_{GE} = 15\text{ V}$, $I_C = 12\text{ A}$	-	4.04	4.46	
		$V_{GE} = 15\text{ V}$, $I_C = 6\text{ A}$, $T_J = 125\text{ }^{\circ}\text{C}$	-	3.45	3.60	
		$V_{GE} = 15\text{ V}$, $I_C = 12\text{ A}$, $T_J = 125\text{ }^{\circ}\text{C}$	-	5.07	5.32	
Gate threshold voltage	$V_{GE(th)}$	$I_C = 250\text{ }\mu\text{A}$	4	-	6	
Temperature coefficient of threshold voltage	$\Delta V_{GE(th)}/\Delta T_J$	$V_{CE} = V_{GE}$, $I_C = 1\text{ mA}$ ($25\text{ }^{\circ}\text{C}$ to $125\text{ }^{\circ}\text{C}$)	-	- 10	-	mV/ $^{\circ}\text{C}$
Forward transconductance	g_{fe}	$V_{CE} = 25\text{ V}$, $I_C = 6\text{ A}$	-	3.2	-	S
Collector to emitter leaking current	I_{CES}	$V_{GE} = 0\text{ V}$, $V_{CE} = 1200\text{ V}$	-	-	250	μA
		$V_{GE} = 0\text{ V}$, $V_{CE} = 1200\text{ V}$, $T_J = 125\text{ }^{\circ}\text{C}$	-	-	1000	
Diode forward voltage drop	V_{FM}	$I_F = 6\text{ A}$, $V_{GE} = 0\text{ V}$	-	2.33	2.77	V
		$I_F = 12\text{ A}$, $V_{GE} = 0\text{ V}$	-	3.01	3.63	
		$I_F = 6\text{ A}$, $V_{GE} = 0\text{ V}$, $T_J = 125\text{ }^{\circ}\text{C}$	-	2.55	2.98	
		$I_F = 12\text{ A}$, $V_{GE} = 0\text{ V}$, $T_J = 125\text{ }^{\circ}\text{C}$	-	3.45	4.07	
Gate to emitter leakage current	I_{GES}	$V_{GE} = \pm 20\text{ V}$	-	-	± 250	nA

SWITCHING CHARACTERISTICS ($T_J = 25\text{ }^{\circ}\text{C}$ unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Total gate charge (turn-on)	Q_g	$I_C = 6\text{ A}$ $V_{CC} = 600\text{ V}$ $V_{GE} = 15\text{ V}$	-	27	41	nC
Gate to emitter charge (turn-on)	Q_{ge}		-	3.7	5.6	
Gate to collector charge (turn-on)	Q_{gc}		-	14	21	
Turn-on switching loss	E_{on}	$I_C = 6\text{ A}$, $V_{CC} = 600\text{ V}$, $V_{GE} = 15\text{ V}$ $R_g = 10\text{ }\Omega$, $L = 2.0\text{ mH}$, $T_J = 25\text{ }^{\circ}\text{C}$ Energy losses include tail and diode reverse recovery	-	0.606	0.909	mJ
Turn-off switching loss	E_{off}		-	0.340	0.510	
Total switching loss	E_{tot}		-	0.946	1.420	
Turn-on switching loss	E_{on}	$I_C = 6\text{ A}$, $V_{CC} = 600\text{ V}$, $V_{GE} = 15\text{ V}$ $R_g = 10\text{ }\Omega$, $L = 2.0\text{ mH}$, $T_J = 125\text{ }^{\circ}\text{C}$ Energy losses include tail and diode reverse recovery	-	0.779	1.170	mJ
Turn-off switching loss	E_{off}		-	0.403	0.605	
Total switching loss	E_{tot}		-	1.182	1.775	
Turn-on delay time	$t_{d(on)}$	$I_C = 6\text{ A}$, $V_{CC} = 600\text{ V}$, $V_{GE} = 15\text{ V}$ $L = 2.0\text{ mH}$, $L_S = 100\text{ nH}$ $R_g = 10\text{ }\Omega$, $T_J = 125\text{ }^{\circ}\text{C}$	-	47	71	ns
Rise time	t_r		-	17	26	
Turn-off delay time	$t_{d(off)}$		-	99	150	
Fall time	t_f		-	362	543	
Reverse BIAS safe operating area	RBSOA	$T_J = 150\text{ }^{\circ}\text{C}$, $I_C = 24\text{ A}$ $R_g = 10\text{ }\Omega$, $V_{GE} = 15\text{ V}$ to 0	Fullsquare			
Short circuit safe operating area	SCSOA	$V_{CC} = 600\text{ V}$, $V_{GE} = + 15\text{ V}$ to 0 $T_J = 150\text{ }^{\circ}\text{C}$, $V_P = 1200\text{ V}$, $R_g = 10\text{ }\Omega$	10	-	-	μs
Input capacitance	C_{ies}	$V_{GE} = 0\text{ V}$ $V_{CC} = 30\text{ V}$ $f = 1\text{ MHz}$	-	369	554	pF
Output capacitance	C_{oes}		-	244	366	
Reverse transfer capacitance	C_{res}		-	12	18	
Diode reverse recovery energy	E_{rec}	$I_C = 6\text{ A}$, $V_{CC} = 600\text{ V}$, $V_{GE} = 15\text{ V}$ $L = 2.0\text{ mH}$, $L_S = 100\text{ nH}$ $R_g = 10\text{ }\Omega$, $T_J = 125\text{ }^{\circ}\text{C}$	-	334	-	μJ
Diode reverse recovery time	t_{rr}		-	54	-	ns
Diode peak reverse current	I_{rr}		-	17	-	A

**THERMISTOR SPECIFICATIONS (T CODE ONLY)**

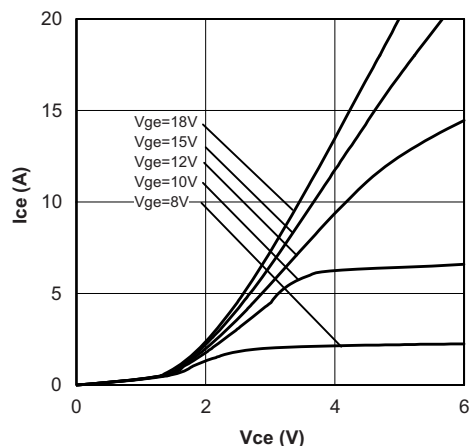
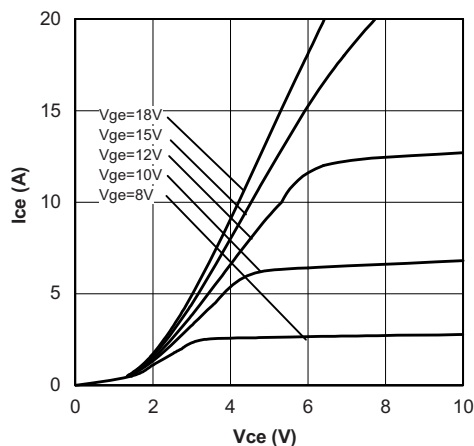
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Resistance	R_0 ⁽¹⁾	$T_0 = 25\text{ }^\circ\text{C}$	-	30	-	k Ω
Sensitivity index of the thermistor material	β ⁽¹⁾⁽²⁾	$T_0 = 25\text{ }^\circ\text{C}$ $T_1 = 85\text{ }^\circ\text{C}$	-	4000	-	K

Notes(1) T_0 , T_1 are thermistor's temperatures

$$(2) \frac{R_0}{R_1} = \exp\left[\beta\left(\frac{1}{T_0} - \frac{1}{T_1}\right)\right]$$

THERMAL AND MECHANICAL SPECIFICATIONS

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Operating junction temperature range	T_J		- 40	-	150	$^\circ\text{C}$
Storage temperature range	T_{Stg}		- 40	-	125	
Junction to case — IGBT	R_{thJC}		-	-	2.68	$^\circ\text{C/W}$
Diode			-	-	4.2	
Case to sink per module	R_{thCS}	Heatsink compound thermal conductivity = 1 W/mK	-	0.06	-	
Mounting torque			-	-	4	Nm
Weight			-	65	-	g

Fig. 1 - Typical Output Characteristics
 $T_J = 25\text{ }^\circ\text{C}$ Fig. 2 - Typical Output Characteristics
 $T_J = 125\text{ }^\circ\text{C}$

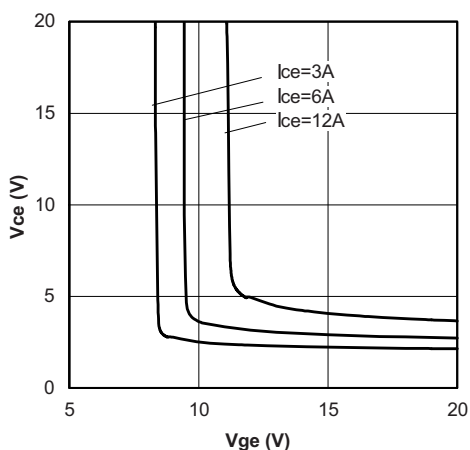


Fig. 3 - Typical V_{CE} vs. V_{GE}
 $T_J = 25^\circ\text{C}$

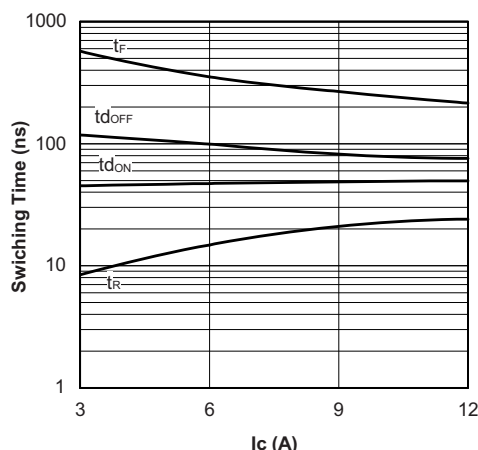


Fig. 6 - Typical Switching Time vs. I_C
 $T_J = 125^\circ\text{C}$, $L = 2\text{ mH}$, $V_{CE} = 600\text{ V}$
 $R_g = 10\ \Omega$; $V_{GE} = 15\text{ V}$

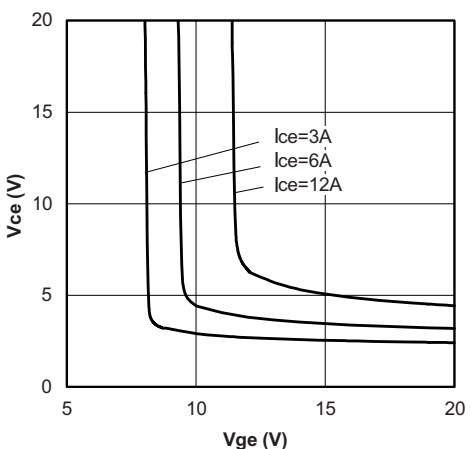


Fig. 4 - Typical V_{CE} vs. V_{GE}
 $T_J = 125^\circ\text{C}$

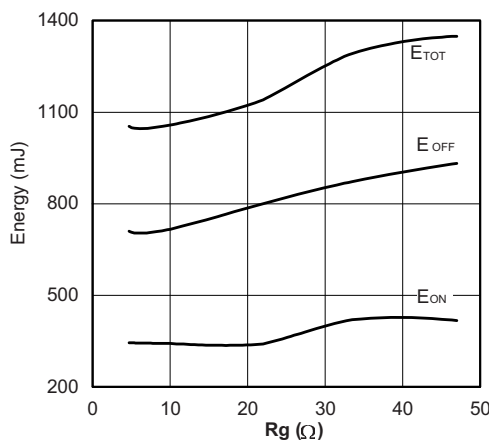


Fig. 7 - Typical Energy Loss vs. R_g
 $T_J = 125^\circ\text{C}$, $L = 2\text{ mH}$, $V_{CE} = 600\text{ V}$
 $I_C = 6\text{ A}$; $V_{GE} = 15\text{ V}$

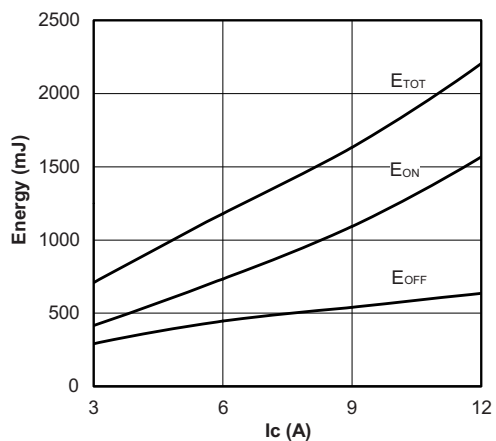


Fig. 5 - Typical Energy Loss vs. I_C
 $T_J = 125^\circ\text{C}$, $L = 2\text{ mH}$, $V_{CE} = 600\text{ V}$
 $R_g = 10\ \Omega$; $V_{GE} = 15\text{ V}$

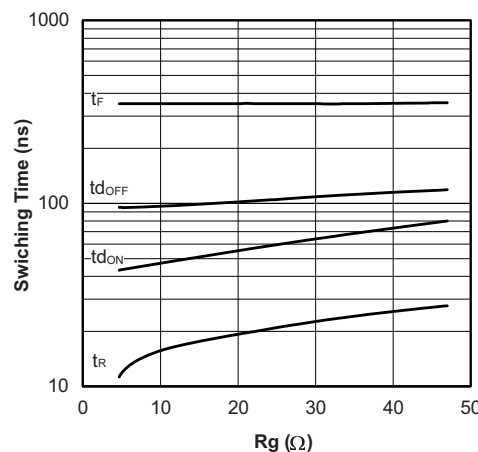


Fig. 8 - Typical Switching Time vs. R_g
 $T_J = 125^\circ\text{C}$, $L = 2\text{ mH}$, $V_{CE} = 600\text{ V}$
 $I_C = 6\text{ A}$; $V_{GE} = 15\text{ V}$

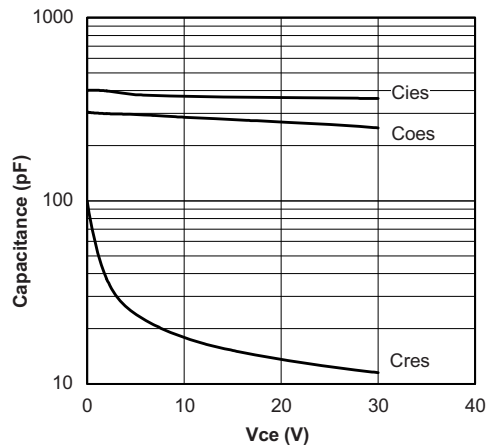


Fig. 9 - Typical Capacitance vs. V_{CE}
 $V_{GE} = 0\text{ V}$; $f = 1\text{ MHz}$

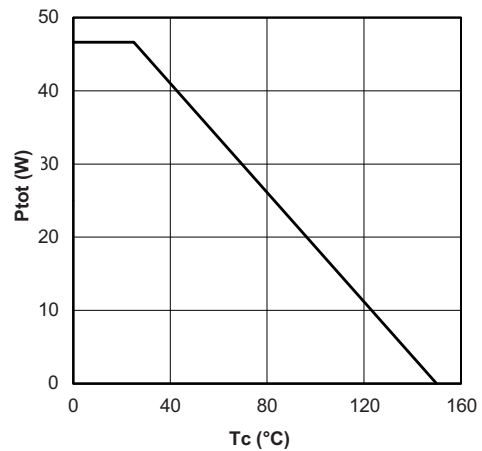


Fig. 12 - Power Dissipation vs. Case Temperature
 (IGBT only)

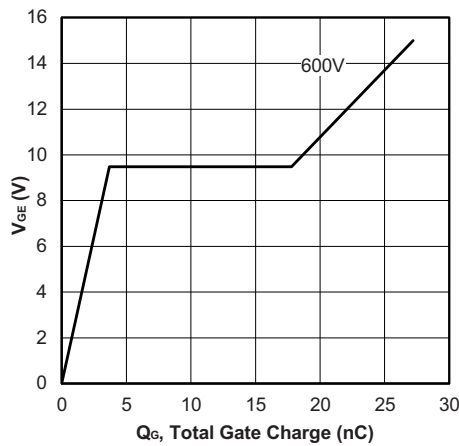


Fig. 10 - Typical Gate Charge vs. V_{GE}
 $I_{CE} = 5\text{ A}$

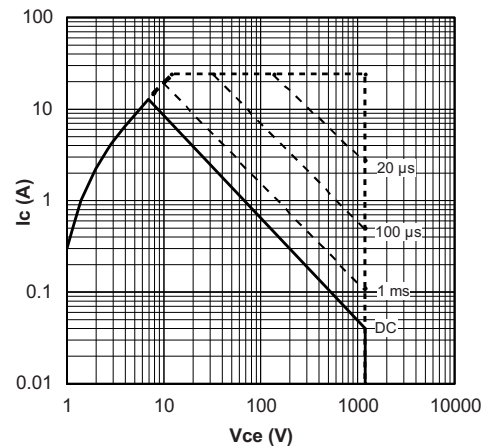


Fig. 13 - Forward SOA
 $T_C = 25\text{ °C}$, $T_J \leq 150\text{ °C}$

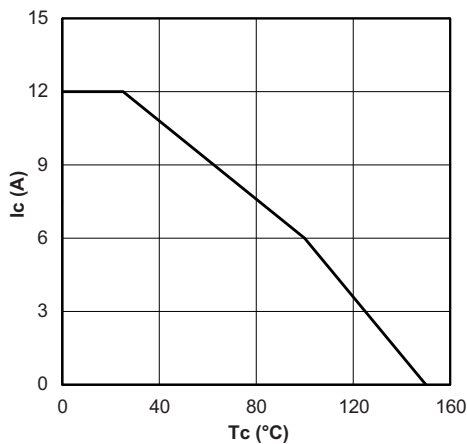


Fig. 11 - Maximum DC Collector Current vs.
 Case Temperature

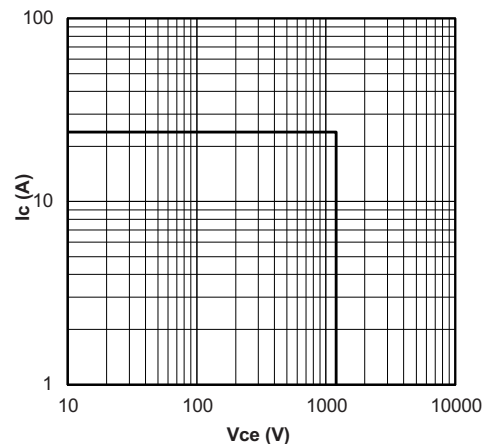


Fig. 14 - Reverse BIAS SOA
 $T_J = 150\text{ °C}$, $V_{GE} = 15\text{ V}$

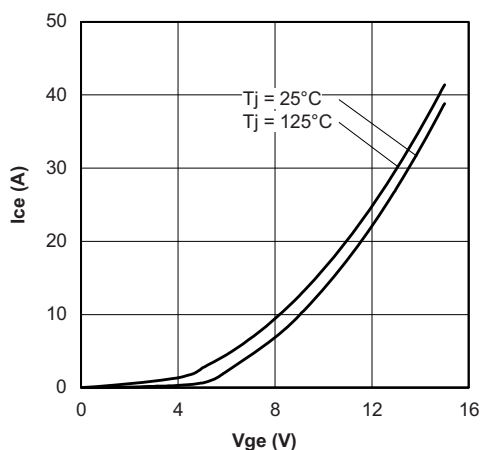


Fig. 15 - Typical Transfer Characteristics
 $V_{CE} = 50 \text{ V}$; $t_p = 10 \mu\text{s}$

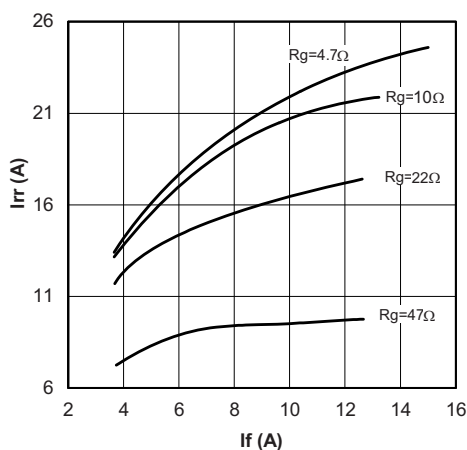


Fig. 17 - Typical Diode I_{rr} vs. I_F
 $T_J = 125^\circ\text{C}$

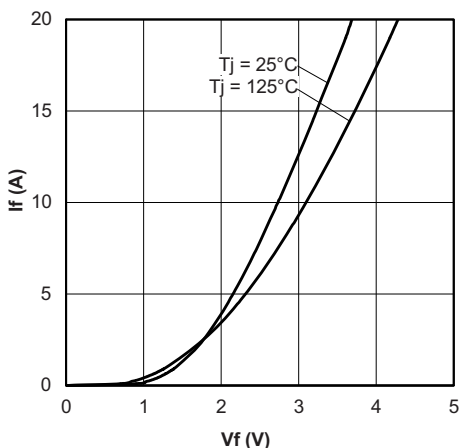


Fig. 16 - Typical Diode Forward Characteristics
 $t_p = 80 \mu\text{s}$

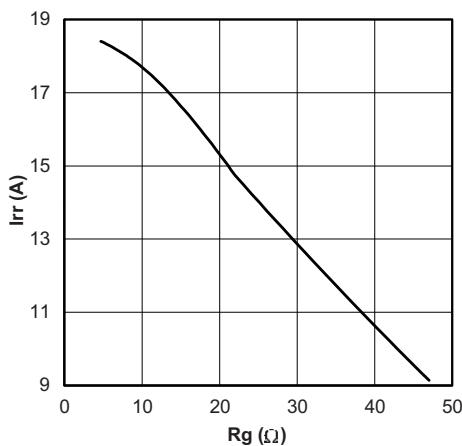


Fig. 18 - Typical Diode I_{rr} vs. R_g
 $T_J = 125^\circ\text{C}$; $I_F = 10 \text{ A}$

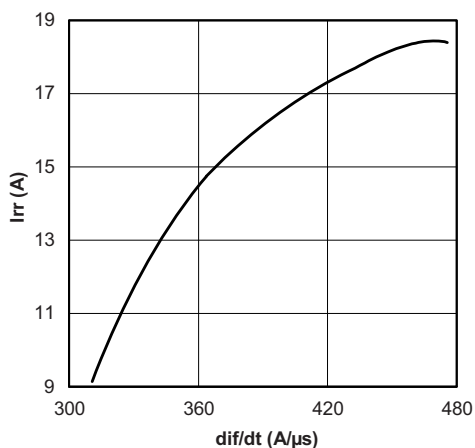


Fig. 19 - Typical Diode I_{rr} vs. dI_F/dt ; $V_{CC} = 600 \text{ V}$;
 $V_{GE} = 15 \text{ V}$; $I_{CE} = 10 \text{ A}$; $T_J = 125^\circ\text{C}$

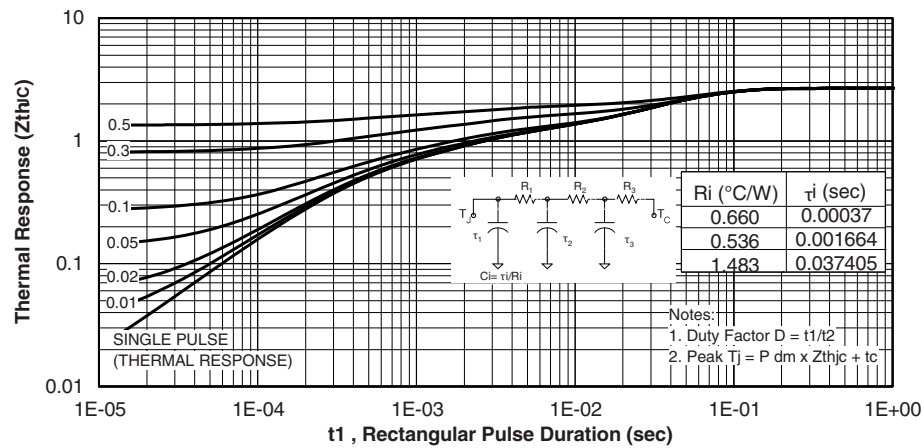


Fig. 20 - Maximum Transient Thermal Impedance, Junction to Case (IGBT)

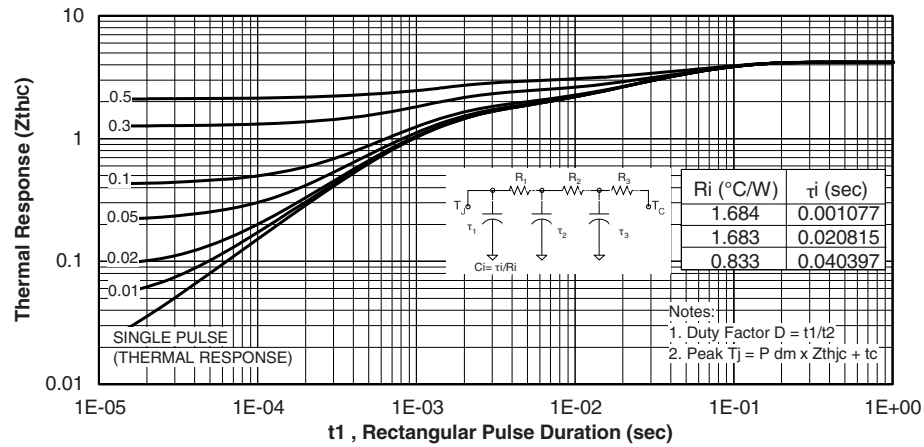


Fig. 21 - Maximum Transient Thermal Impedance, Junction to Case (Diode)

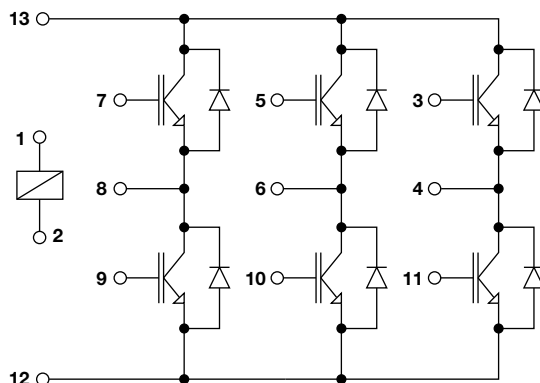


ORDERING INFORMATION TABLE

Device code	VS-	GB	05	XP	120	K	T	PbF
	1	2	3	4	5	6	7	8

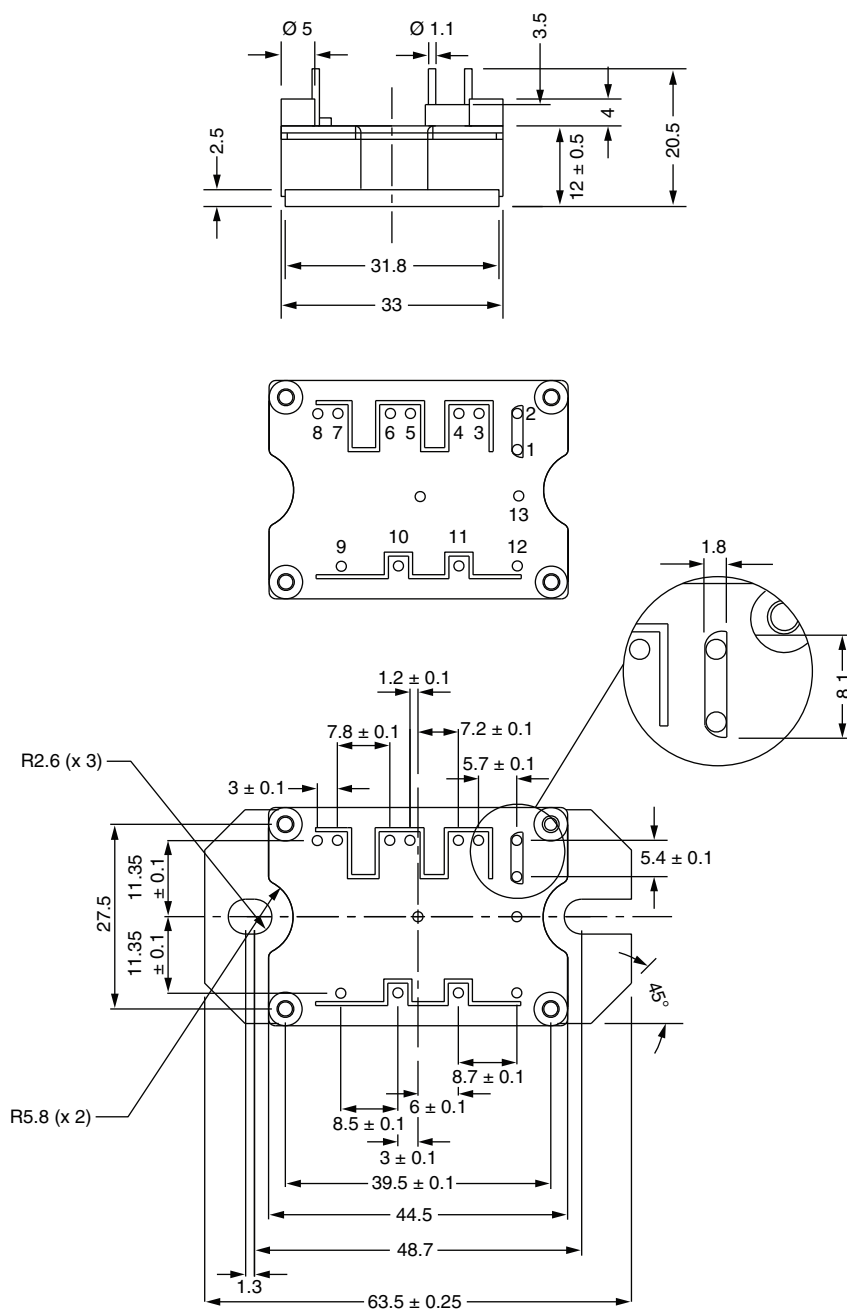
- | | | |
|----------|---|---|
| 1 | - | Vishay Semiconductors product |
| 2 | - | IGBT module |
| 3 | - | Nominal current rating (05 = 5 A) |
| 4 | - | Circuit configuration (XP = Sixpack MTP package) |
| 5 | - | Voltage code (120 = 1200 V) |
| 6 | - | Speed/type (K = Ultrafast IGBT/inverter motor drive application) |
| 7 | - | Special option: <ul style="list-style-type: none">• None = No special option• T = Thermistor |
| 8 | - | PbF = Lead (Pb)-free |

CIRCUIT CONFIGURATION



LINKS TO RELATED DOCUMENTS	
Dimensions	www.vishay.com/doc?95175

DIMENSIONS in millimeters



- Unused terminals are not assembled in the package



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